NEC

MOS FIELD EFFECT TRANSISTOR
2SK2826

SWITCHING
N-CHANNEL POWER MOS FET
INDUSTRIAL USE

DESCRIPTION

This product is N-Channel MOS Field Effect Transistor designed for high current switching applications.

ORDERING INFORMATION

PART NUMBER	PACKAGE
2SK2826	TO-220AB
2SK2826-S	TO-262
2SK2826-ZJ	TO-263

FEATURES

- Super Low On-State Resistance
  $R_{DS(on)1}$ = 6.5 mΩ (MAX.) (V_{GS} = 10 V, I_D = 35 A)
  $R_{DS(on)2}$ = 9.7 mΩ (MAX.) (V_{GS} = 4.0 V, I_D = 35 A)
- Low C_{iss} : C_{iss} = 7200 pF (TYP.)
- Built-in Gate Protection Diode

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C)

Drain to Source Voltage (V_{GS} = 0 V)	V_{DSS}	60	V
Gate to Source Voltage (V_{DS} = 0 V)	$V_{GSS(AC)}$	±20	V
Gate to Source Voltage (V_{DS} = 0 V)	$V_{GSS(DC)}$	+20, –10	V
Drain Current (DC)	$I_{D(DC)}$	±70	A
Drain Current (Pulse) Note1	$I_{D(pulse)}$	±280	A
Total Power Dissipation (T_C = 25°C)	P_T	100	W
Total Power Dissipation (T_A = 25°C)	P_T	1.5	W
Channel Temperature	T_{ch}	150	°C
Storage Temperature	T_{stg}	–55 to + 150	°C
Single Avalanche Current Note2	I_{AS}	70	A
Single Avalanche Energy Note2	E_{AS}	490	mJ

Notes 1. PW ≤ 10 μs, Duty cycle ≤ 1 %

2. Starting Tch = 25 °C, R_A = 25 Ω, V_{GS} = 20 V → 0 V

THERMAL RESISTANCE

Channel to Case	R_{th}(ch-C)	1.25	°C/W
Channel to Ambient	R_{th}(ch-A)	83.3	°C/W

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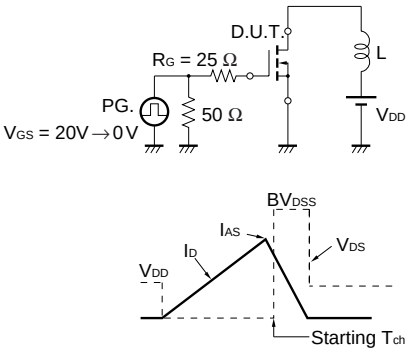
The mark ★ shows major revised points.

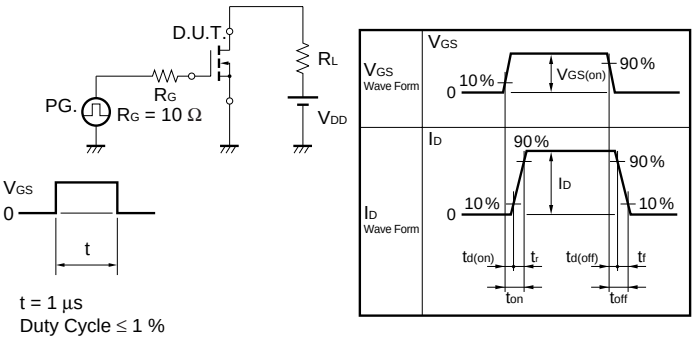
ELECTRICAL CHARACTERISTICS (T_A = 25 °C)

	CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
★	Drain to Source On-state Resistance	$R_{DS(on)1}$	V_{GS} = 10 V, I_D = 35 A		5.5	6.5	mΩ
		$R_{DS(on)2}$	V_{GS} = 4.0 V, I_D = 35 A		7.0	9.7	mΩ
	Gate to Source Cut-off Voltage	$V_{GS(off)}$	V_{DS} = 10 V, I_D = 1 mA	1.0	1.5	2.0	V
	Forward Transfer Admittance	$\|y_{fs}\|$	V_{DS} = 10 V, I_D = 35 A	20	94		S
	Drain Leakage Current	I_{DSS}	V_{DS} = 60 V, V_{GS} = 0 V			10	μA
	Gate to Source Leakage Current	I_{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V			±10	μA
	Input Capacitance	C_{iss}	V_{DS} = 10 V		7200		pF
	Output Capacitance	C_{oss}	V_{GS} = 0 V		2000		pF
	Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		700		pF
★	Turn-on Delay Time	$t_{d(on)}$	I_D = 35 A		100		ns
★	Rise Time	t_r	$V_{GS(on)}$ = 10 V		1200		ns
★	Turn-off Delay Time	$t_{d(off)}$	V_{DD} = 30 V		440		ns
★	Fall Time	t_f	R_G = 10 Ω		520		ns
	Total Gate Charge	Q_G	I_D = 70 A		150		nC
	Gate to Source Charge	Q_{GS}	V_{DD} = 48 V		20		nC
	Gate to Drain Charge	Q_{GD}	V_{GS} = 10 V		40		nC
	Body Diode Forward Voltage	$V_{F(S-D)}$	I_F = 70 A, V_{GS} = 0 V		0.97		V
	Reverse Recovery Time	t_{rr}	I_F = 70 A, V_{GS} = 0 V		80		ns
	Reverse Recovery Charge	Q_{rr}	di/dt = 100A/μs		250		nC

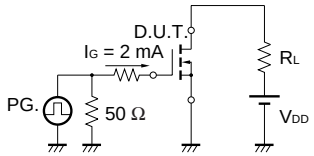
TEST CIRCUIT 1 AVALANCHE CAPABILITY



TEST CIRCUIT 2 SWITCHING TIME

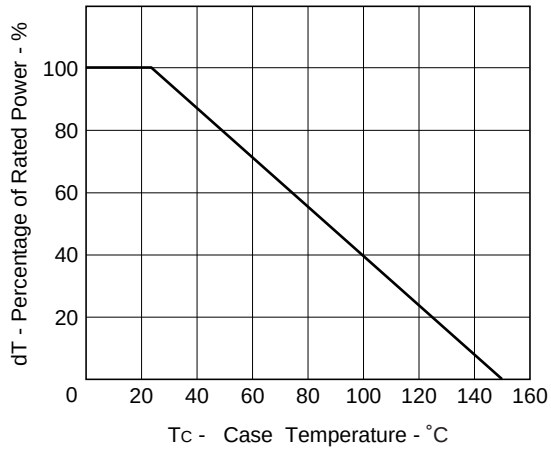


TEST CIRCUIT 3 GATE CHARGE

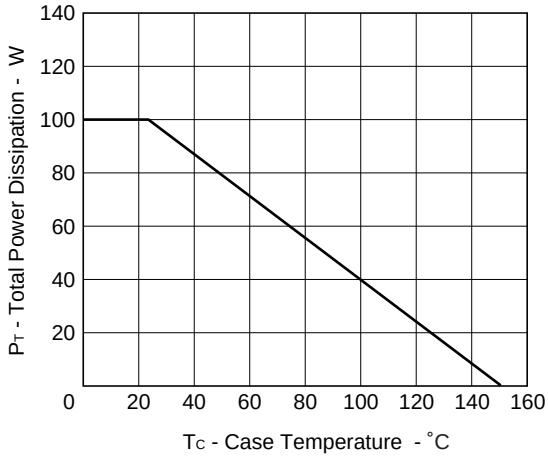


TYPICAL CHARACTERISTICS (T_A = 25 °C)

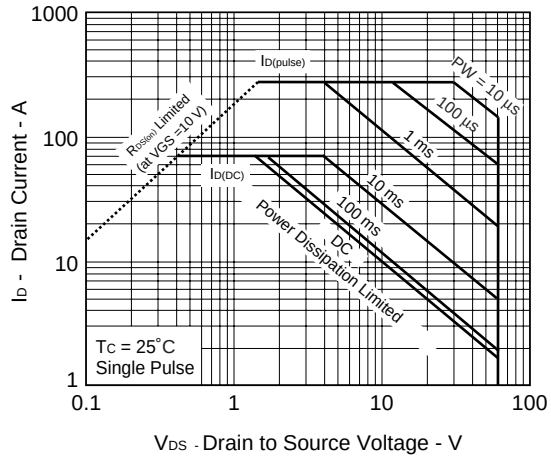
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



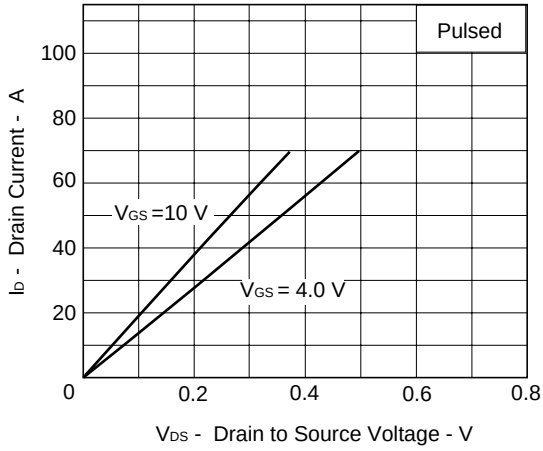
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



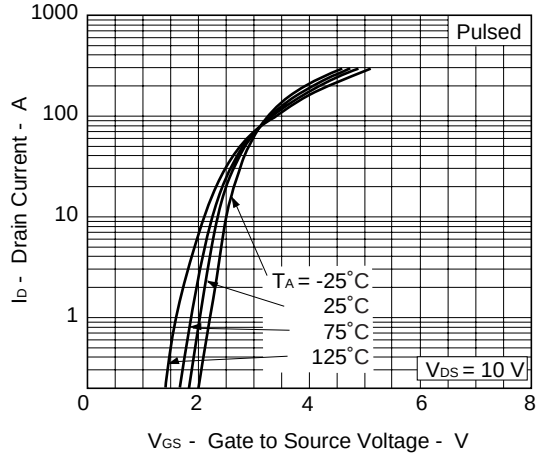
FORWARD BIAS SAFE OPERATING AREA



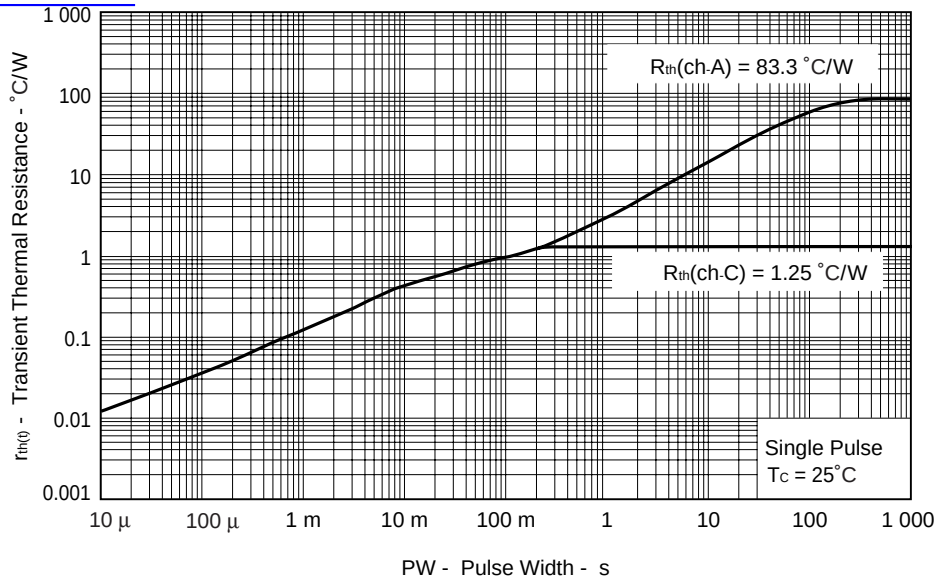
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



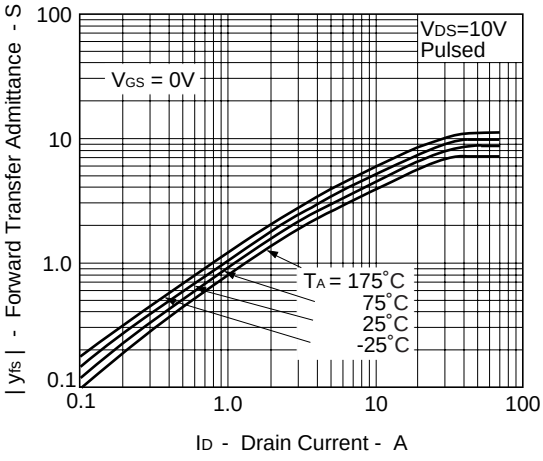
FORWARD TRANSFER CHARACTERISTICS



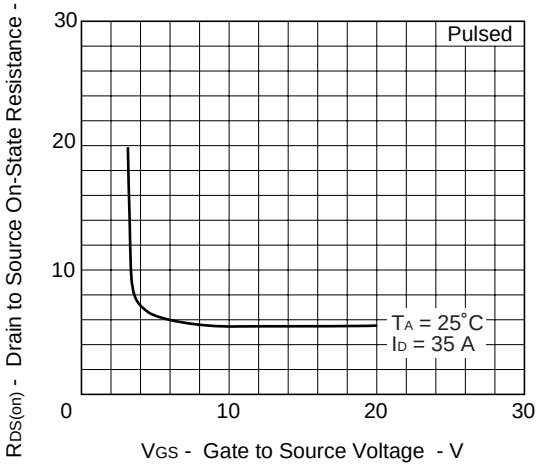
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



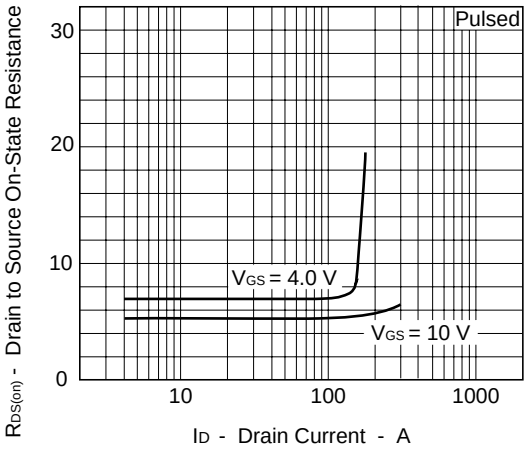
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



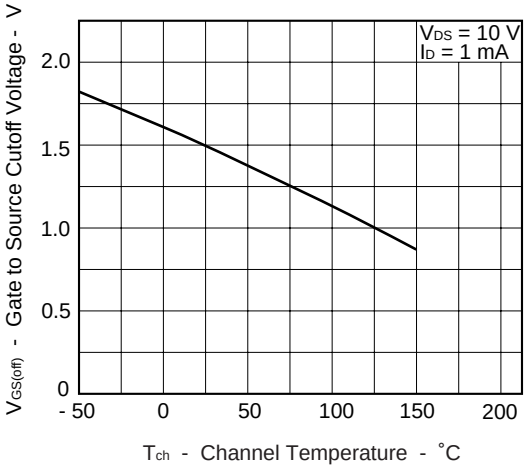
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



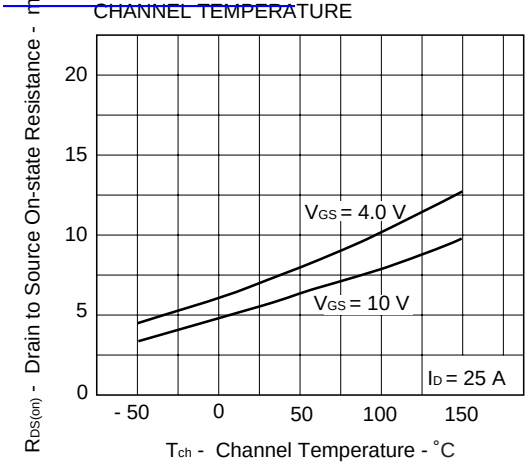
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



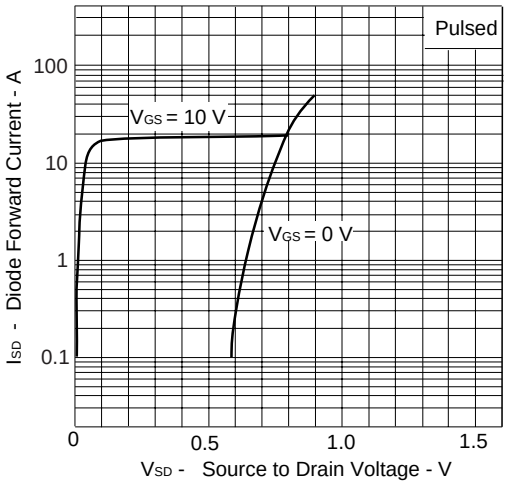
GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



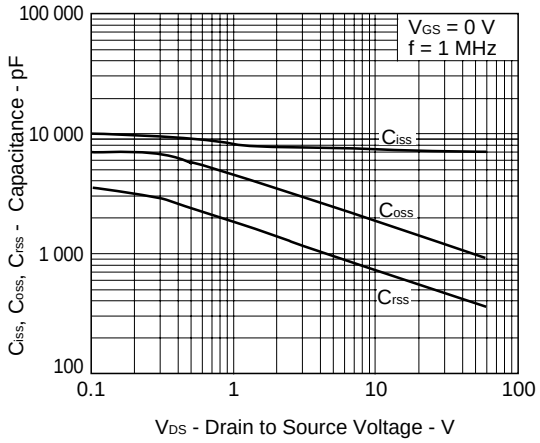
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



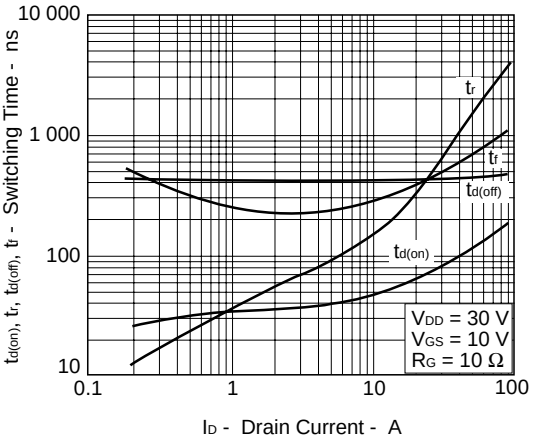
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



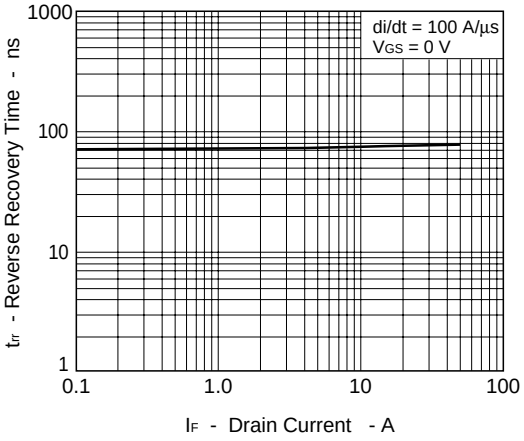
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



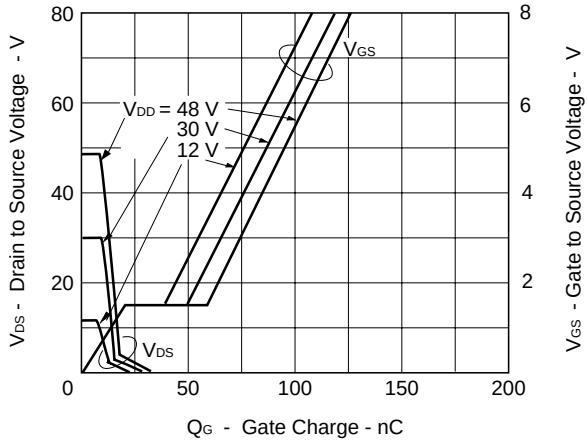
★ SWITCHING CHARACTERISTICS



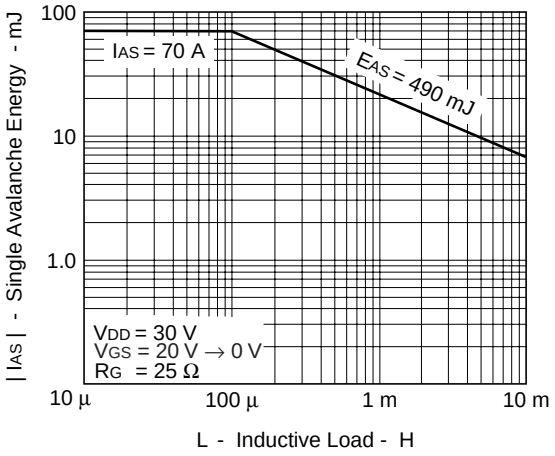
REVERSE RECOVERY TIME vs. DRAIN CURRENT



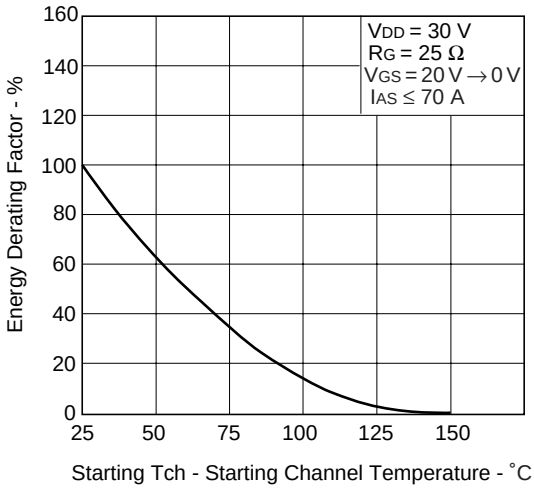
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



SINGLE AVALANCHE ENERGY vs.
INDUCTIVE LOAD

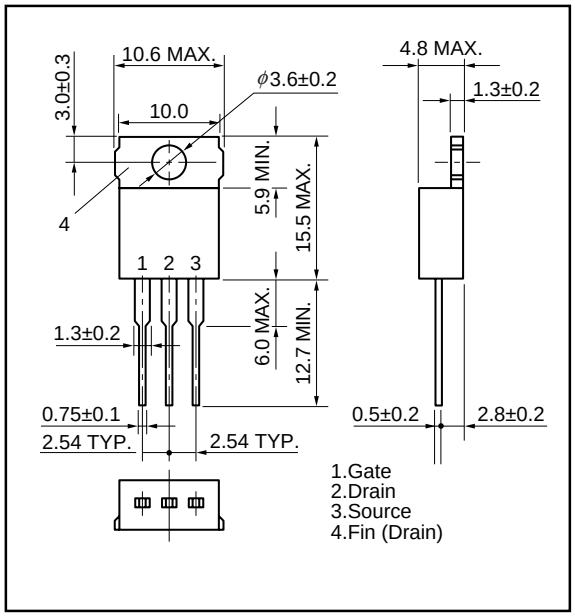


SINGLE AVALANCHE ENERGY
DERATING FACTOR

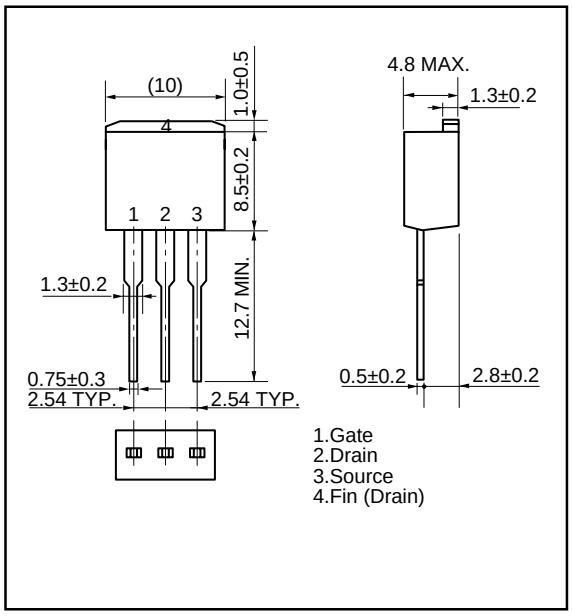


PACKAGE DRAWINGS (Unit : mm)

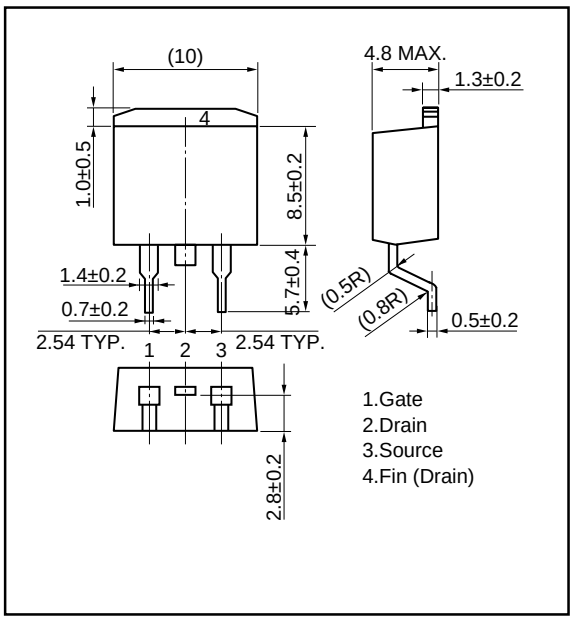
1)TO-220AB (MP-25)



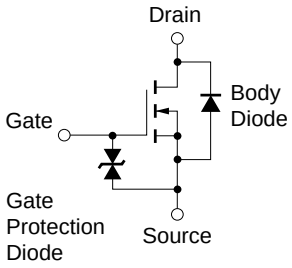
2)TO-262 (MP-25 Fin Cut)



3)TO-263 (MP-25ZJ)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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